Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D
			***: Required Field**

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	2023-02-02
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Signature Not Verified

Digitally signed by MDF Champion
Date: 2023.02.02 08:58:09 +08:00

Product

Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U575ZIT6 STM32U575ZIT6TR	E01A*482XXXW	A	9991	2023-02-02
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	1315.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information

J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	20x20	144	L bend	
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015

Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	Description

QueryList : REACH-10 Jun 2022

Query	Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**E01A*482XXXW**					6000001.0	999999.7
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**	
Die or dies	M-011 Other inorganic materials	14.898	mg	supplier	die	Silicon (Si)	7440-21-3		14.327	mg	961673	10895	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.063	mg	4229	48	
				supplier	metallization	Copper (Cu)	7440-50-8		0.188	mg	12619	143	
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	67	1	
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.032	mg	2148	24	
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	537	6	
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	67	1	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.045	mg	3021	34	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.233	mg	15640	177	
Leadframe (C7025)	Copper & its alloys	330.000	mg	supplier	Leadframe	Copper (Cu)	7440-50-8		315.975	mg	957500	240285	
				supplier	Leadframe	Nickel (Ni)	7440-02-0		9.834	mg	29800	7478	
				supplier	Leadframe	Silicon (Si)	7440-21-3		2.145	mg	6500	1631	
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		0.495	mg	1500	376	
				supplier	Leadframe	Siliver (Ag)	7440-22-4		1.551	mg	4700	1179	
Glue (CRM-1076WA)	Precious metals	3.001	mg	supplier	Glue or tape	Silver Powder	7440-22-4		2.307	mg	768744	1754	
				supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.090	mg	29990	68	
				supplier	Glue or tape	Epoxy resin	Trade Secret		0.195	mg	64978	148	
				supplier	Glue or tape	Diluent	Trade Secret		0.060	mg	19993	46	
				supplier	Glue or tape	Ethylene dimethacrylate	97-90-5		0.225	mg	74975	171	
				supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.090	mg	29990	68	
				supplier	Glue or tape	Dicyandiamide	461-58-5		0.017	mg	5665	13	
				supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.017	mg	5665	13	
Bonding Wire (Au 0.8 Mils)	Precious metals	3.001	mg	supplier	Bonding wire	Au	7440-57-5		2.966	mg	988337	2256	
				supplier	Bonding wire	Palladium	7440-05-3		0.035	mg	11663	27	
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	952.600	mg	supplier	Molding Compound	Epoxy Resin A	Proprietary		9.526	mg	10000	7244	
				supplier	Molding Compound	Epoxy Resin B	Proprietary		9.526	mg	10000	7244	
				supplier	Molding Compound	Phenol Resin	Proprietary		71.445	mg	75000	54331	
				supplier	Molding Compound	Carbon Black	1333-86-4		5.239	mg	5500	3984	
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		713.974	mg	749500	542946	
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		142.890	mg	150000	108662	
External Plating	M-011 Other inorganic materials	11.500	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		11.499	mg	999913	8744	
				supplier	Matte Sn	Impurities	Proprietary		0.001	mg	87	1	